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ABSTRACT OF THE INVENTION

The invention relates to a ball-limiting metallurgy stack for an electrical device that contains at least one copper layer disposed upon a Ti adhesion metal layer. The ball-limiting metallurgy stack resists Sn migration toward the upper metallization of the device.

"Express Mail" mailing label number: <u>EL873859976</u>
Date of Deposit: <u>September 21, 2001</u>
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